

4~8wafers Fully automatic after gringing cleaning manchine

Model: SA-AGCM-48LS

SA-AGCM-48LS is made of high-grade materials to resist acidic corrosive environments. It adopts mature processes to effectively remove grinding residues on wafer surfaces. Equipped with automated manipulators and modular tank structure, it ensures steady operation and uniform processing results. With advanced control configurations and sound leak-proof design, it supports intelligent management and delivers reliable performance for semiconductor production.



Feature

- Long-time Acidic Corrosion Resistant
- Double-layer Leak-proof
- Customize for Manual and Fully Automatic
- Support MES system
- ISO9001 Quality Assurance

Application

- Wafer Front-End Cleaning
- Photolithography Cleaning
- Etch Post-Cleaning
- Thin Film Cleaning
- Back-End Packaging

Specifications:

Parameter	Descriptions
Wafer Size	4"~8"
Cleaning Capacity	25pieces2baskets/batch
Control Part	PLC and HMI